PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chih-Jen Yen	07/02/2007
Chih-Yuan Hsieh	07/02/2007

RECEIVING PARTY DATA

Name:	NOVATEK Microelectronics Corp.	
Street Address:	2F, No. 13, Innovation Rd. I, Hsinchu Science Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11773945	

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	WINSTON HSU

Total Attachments: 2

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PATENT REEL: 019521 FRAME: 0020

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Docket No NVAP0061USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

Name:	Chih-Jen Yen	Nationality: R.O.C.		
Name:	Chih-Yuan Hsieh	Nationality: R.O.C.		
ereby sells, a	assigns and transfers to			
SSIGNEE(S):			
Name:	Name: NOVATEK Microelectronics Corp. Address: 2F, No. 13, Innovation Rd. I, Hsinchu Science Park, Hsin-Chu 300, Taiwan, R.O.			
Address				
	ssors and assignees of the A provements which are disclo	SSIGNEE the entire right, title, and interest in and to sed in the invention entitled:		
"Opera	ntional Amplifier Capabl	e of Compensating Offset Voltage"		
Which is fou	nd in :			
(a) <u>+</u>	U.S. patent application exec	uted on even date		
(b)	U.S. patent application exec	auted on		
()	U.S. application serial no			
(C)				

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NPO#NVA-P0061-USA:0 CUST#NVT-2006-128 F#NPO-P0002E-US1 DSB0-096U010577

PATENT REEL: 019521 FRAME: 0021

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

| Signature of Inventor | Chih-Yuan Hsieh | Chih-Yuan Hsieh | JUL 0 2 2007 | JUL 0 2 2007 | JUL 0 2 2007 | Date of Signing). (本年1年日本・)

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RECORDED: 07/06/2007

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PATENT REEL: 019521 FRAME: 0022